


APPLICATION DATA SHEET

Electronic Version v14

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Title of Invention	WAFER LEVEL MICROELECTRONIC PACKAGING WITH DOUBLE ISOLATION		
Application Type : regular, utility Attorney Docket Number : TESSERA 3.0-395			
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Inventors Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: GB Given Name: Giles Family Name: Humpston Residence: City of Residence: San Jose State of Residence: CA Country of Residence: US Address-1 of Mailing Address: 6226 Paso Los Cerritos Address-2 of Mailing Address: City of Mailing Address: San Jose State of Mailing Address: CA Postal Code of Mailing Address: 95120 Country of Mailing Address: US Phone: Fax: E-mail: <u>Inventor 2:</u> Applicant Authority Type: Inventor Citizenship: US Given Name: Bruce Family Name: McWilliams Residence:			

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